

## Flat Pack

### Ceramic Flat Pack Package (FP)

Amkor Technology is committed to continuing to service this long established standard industry package. This surface mount package consists of a co-fired ceramic base that has leads brazed to either the top or bottom of the package. The lid for this package can be either ceramic "frit sealed" or metal "solder sealed". This package provides a hermetic environment for the IC inside.

### Applications:

This IC package technology allows application and design engineers to maximize the performance characteristics of semiconductors (silicon, GaAs and S.A.W.). These packages enable end products (pagers, portable audio/video, disc drives, radio, IF & RF devices/components, telecom) to be reduced in size and weight. Semiconductor families such as operational amplifiers, drivers, optoelectronics, controllers, logic, analog, memory, comparators and more using BiCMOS, CMOS or other silicon/GaAs/S.A.W. technologies are well addressed by the LLCC product family.

### Features:

The Flat Pack package offers a variety of features for the semiconductor IC industry and Amkor provides a platform from prototype-to-production:

- Flexible lead / pin counts
- Variety of body sizes
- Hermetic package
- Exceptional thermal and electrical performance by design
- Multi-layer, ground / power
- Cavity Up / Cavity down configurations
- Cavity package

